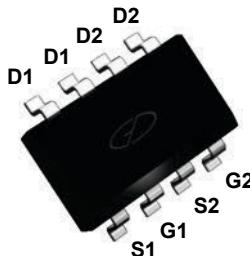
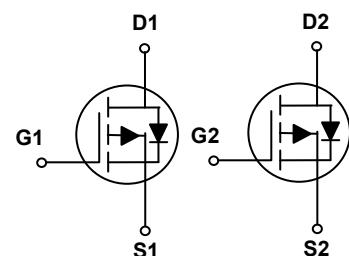


Main Product Characteristics

| | |
|---------------|-------|
| $V_{(BR)DSS}$ | -30V |
| $R_{DS(ON)}$ | 58mΩ |
| I_D | -5.4A |



SOP-8



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFQ4953 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|-----------------|-------------|------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-to-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, @ Steady-State ($T_A=150^\circ\text{C}$) ¹ | I_D | -5.4 | A |
| Pulsed Drain Current ² | I_{DM} | -20 | A |
| Power Dissipation | P_D | 2 | W |
| Junction-to-Ambient (PCB Mounted, Steady-State) ³ | $R_{\theta JA}$ | 50 | °C/W |
| Operating Junction and Storage Temperature Range | T_J/T_{STG} | -55 to +150 | °C |

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|-----------------------------|---|------|------|------|------------------|
| On / Off Characteristics | | | | | | |
| Drain-to-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}}=0\text{V}, I_D=-250\mu\text{A}$ | -30 | - | - | V |
| Drain-to-Source Leakage Current | I_{DSS} | $V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | -1 | μA |
| Gate-to-Source Forward Leakage | I_{GSS} | $V_{\text{GS}}=20\text{V}$ | - | - | 100 | nA |
| | | $V_{\text{GS}}=-20\text{V}$ | - | - | -100 | |
| Static Drain-to-Source On-Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=-10\text{V}, I_D=-5.3\text{A}$ | - | 44 | 58 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=-4.5\text{V}, I_D=-4\text{A}$ | | 54 | 85 | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_D=-250\mu\text{A}$ | -1.1 | -1.6 | -2.5 | V |
| Forward Transconductance | g_{fs} | $V_{\text{DS}}=-10\text{V}, I_D=-5\text{A}$ | - | 11 | - | S |
| Dynamic and Switching Characteristic | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}$ $F=1\text{MHz}$ | - | 514 | - | pF |
| Output Capacitance | C_{oss} | | - | 72 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 61 | - | |
| Total Gate Charge | Q_g | $I_D=-3.6\text{A}, V_{\text{DS}}=-15\text{V},$ $V_{\text{GS}}=-10\text{V}$ | - | 13 | - | nC |
| Gate-to-Source Charge | Q_{gs} | | - | 2.4 | - | |
| Gate-to-Drain ("Miller") Charge | Q_{gd} | | - | 1.8 | - | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{GS}}=-10\text{V}, V_{\text{DS}}=-15\text{V},$ $R_L=5\Omega, R_{\text{GEN}}=6\Omega,$ $I_D=-3\text{A}$ | - | 8.1 | - | nS |
| Rise Time | t_r | | - | 3.5 | - | |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 29.5 | - | |
| Fall Time | t_f | | - | 6.2 | -- | |
| Source-Drain Ratings and Characteristics | | | | | | |
| Diode Forward Voltage | V_{SD} | $I_s=-1.7\text{A}, V_{\text{GS}}=0\text{V}$ | - | - | -1.3 | V |

Notes:

1. Pulse test: Pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062inch.

Typical Electrical and Thermal Characteristic Curves

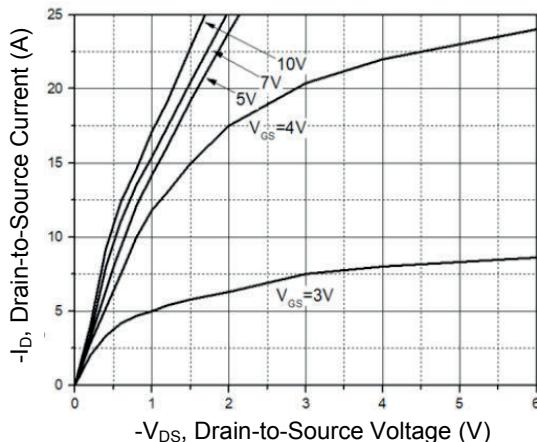


Figure 1. Output Characteristics

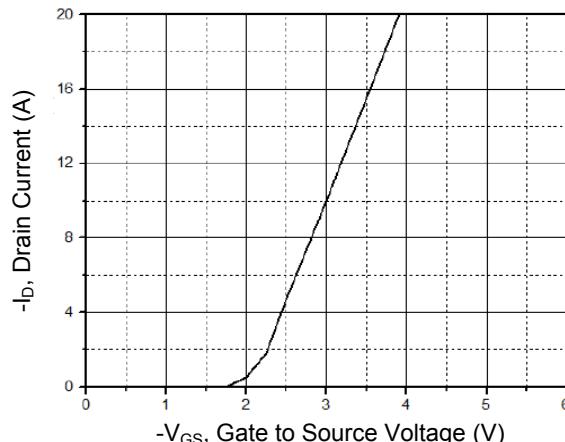


Figure 2. Transfer Characteristics

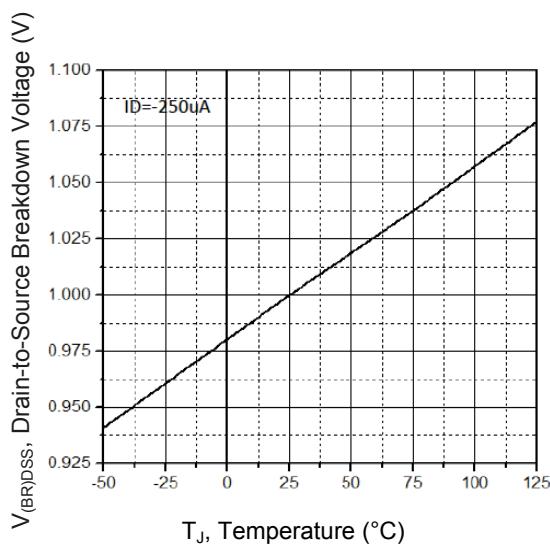


Figure 3. Breakdown Voltage Variation with Temperature

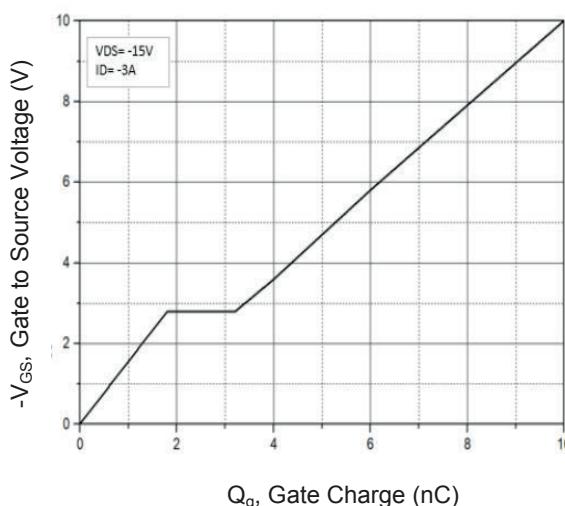


Figure 4. Gate Charge

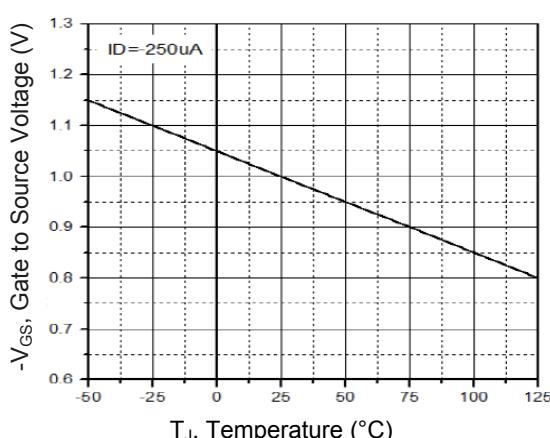


Figure 5. Normalized $V_{GS(th)}$ vs. T_J

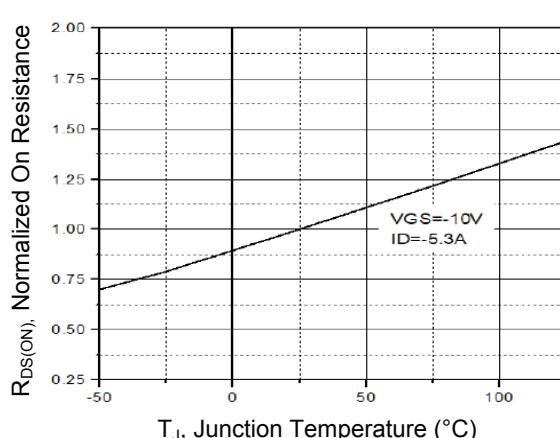


Figure 6. Normalized $R_{DS(ON)}$ vs. T_J

Typical Electrical and Thermal Characteristic Curves

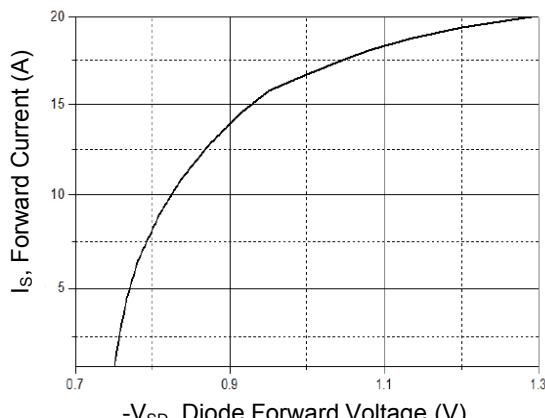


Figure 7. Body Diode Characteristics

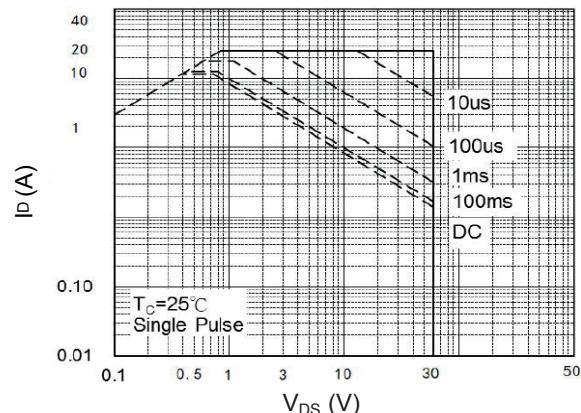
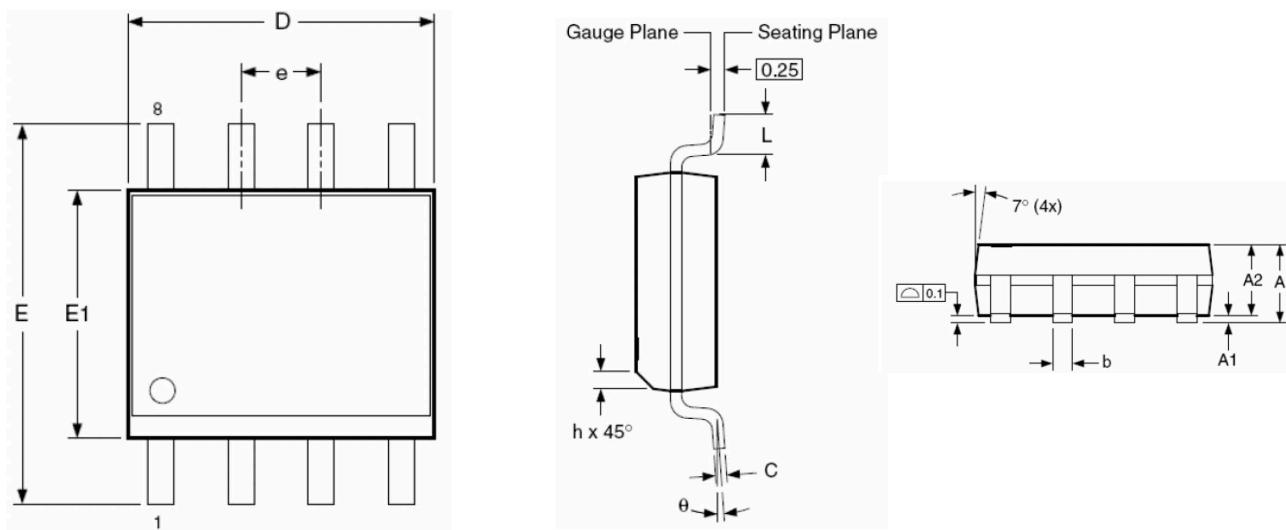


Figure 8. Safe Operation Area

Package Outline Dimensions (SOP-8)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.250 | 1.650 | 0.049 | 0.065 |
| b | 0.310 | 0.510 | 0.012 | 0.020 |
| c | 0.170 | 0.250 | 0.007 | 0.010 |
| D | 4.800 | 5.000 | 0.189 | 0.197 |
| E1 | 3.800 | 4.000 | 0.150 | 0.157 |
| e | 1.270 BSC | | 0.050 BSC | |
| E | 5.800 | 6.200 | 0.228 | 0.244 |
| h | 0.250 | 0.500 | 0.010 | 0.020 |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| θ | 0° | 8° | 0° | 8° |